

Amendments to the Claims:

Claim 16 has been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claims 1-15. (Canceled)

16. (Currently Amended) A package substrate, comprising:
a dielectric film having at least one conductive trace disposed upon a top surface ~~thereof, thereof~~
~~and~~ at least one conductive via formed therethrough, and a first longitudinal slot formed
therethrough; and
an electrically conductive layer adhered to the dielectric film and operably coupled to the at least
one conductive via, the electrically conductive layer comprising:
at least one electrical current isolation slot formed therethrough, at least a part of the
~~electric~~electrical current isolation slot is coextensive with material of the dielectric
film;
a second longitudinal slot formed therethrough through the electrically conductive layer
and substantially aligned with the first longitudinal slot in the dielectric film; and
a surface providing at least one electrical conductor landing area.

17. (Withdrawn) The package substrate of claim 16, further comprising:
a plurality of discrete conductive elements disposed upon the top surface of the dielectric film
bearing the at least one conductive trace, wherein:
at least one of the plurality of discrete conductive elements is operably coupled to the at
least one conductive trace; and
at least one additional discrete conductive element of the plurality is operably coupled to
the at least one conductive via.
18. (Withdrawn) The package substrate of claim 16, wherein the electrically
conductive layer includes metal.
19. (Withdrawn) The package substrate of claim 16, wherein the electrically
conductive layer is thermally conductive.
20. (Withdrawn) The package substrate of claim 16, wherein the electrically
conductive layer provides physical support against torsion and bending of the package substrate.
21. (Withdrawn) The package substrate of claim 16, wherein the electrically
conductive layer is configured to be operably coupled to a voltage source selected from the group
consisting of a ground voltage reference, a power voltage reference, and an intermediate voltage
reference.
22. (Previously Presented) The package substrate of claim 16, wherein the at least
one electrical current isolation slot substantially segments the electrically conductive layer into at
least two segments wherein high frequency noise present on a voltage source in a first segment of
the at least two segments may be substantially isolated from the voltage source in another
segment of the at least two segments.

23. (Withdrawn) The package substrate of claim 16, further comprising;
a longitudinal slot formed through the electrically conductive layer; and
a longitudinal slot formed through the dielectric film having a slot width wider than the
longitudinal slot in the electrically conductive layer such that the at least one electrical
conductor landing area is exposed through the longitudinal slot in the dielectric film.

24. (Withdrawn) The package substrate of claim 23, wherein the at least one
electrical current isolation slot extends from proximate the longitudinal slot formed through the
electrically conductive layer to proximate a lateral peripheral edge of the electrically conductive
layer.

25. (Withdrawn) The package substrate of claim 23, wherein the at least one
electrical current isolation slot extends from and is contiguous with the longitudinal slot formed
through the electrically conductive layer to proximate a lateral peripheral edge of the electrically
conductive layer.

26. (Withdrawn) The package substrate of claim 23, wherein the at least one
electrical current isolation slot intersects and extends from a lateral peripheral edge of the
electrically conductive layer to proximate the longitudinal slot formed through the electrically
conductive layer.

27. (Withdrawn) The package substrate of claim 16, wherein the dielectric film
further comprises a multilayer film having at least one additional layer of conductive traces, at
least one additional dielectric layer and at least one interlayer conductive via effecting connection
between the at least one conductive trace and a conductive trace of the at least one additional
layer of conductive traces.

Claims 28-36. (Canceled)